

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
January Kister	06/18/2010
RECEIVING PARTY DATA	
Name:	MicroProbe, Inc.
Street Address:	2281 Las Palmas Drive
City:	Carlsbad
State/Country:	CALIFORNIA
Postal Code:	92011
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12646661
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Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif	

OP \$40.00 12646661

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PATENT
REEL: 024569 FRAME: 0085

ASSIGNMENT OF INVENTION AND PATENT RIGHTS

Inventor: January Kister
Reissue Serial No. 12/646,661
Filing Date: December 23, 2009

For valuable consideration received or to be received, and hereby acknowledged, **January Kister** of 107 Tan Oak Drive, Portola Valley, California 94028, (hereinafter referred to as "Inventor"), hereby sells, assigns and transfers unto MicroProbe, Inc. of 2281 Las Palmas Drive, Carlsbad, California 92009, its successors and assigns (hereinafter referred to as "Assignee"), the entire interest for the United States of America and all foreign countries, including all rights of priority under the international conventions and treaties, in and to a certain invention or improvement known as Space Transformers Employing Wire Bonds for Interconnections with Fine Pitch Contacts, and described in a Reissue Application filed in the United States Patent and Trademark Office on December 23, 2009, as Attorney Docket No.32811-RE-09, and given U.S. Patent Application Serial No. 12/646,661, which claims priority of U.S. Patent 7,312,617, issued December 25, 2007, Space Transformers Employing Wire Bonds for Interconnections with Fine Pitch Contacts, filed March 20, 2006 and assigned Serial No. 11/385,289, and in all Letters Patent of the United States and all foreign countries which may or shall be granted on said invention, or any parts thereof, or on said application, or on any provisional, utility, divisional, continuing, continuation-in-part, reissue, reexamination or other applications based in whole or in part thereon. And Inventor agrees hereafter to execute all applications, amended specifications, deeds or other instruments, and to do all acts necessary or proper in Assignee's sole discretion to secure to Assignee the grant of Letters Patent in the United States and/or in other countries as Assignee may determine in its sole discretion, with specifications and claims in such form as shall be approved by Assignee's counsel, and to vest and confirm in Assignee the legal and equitable title and full use and benefit of all such patents.

Inventor further agrees with Assignee that this Assignment covers all processes, specifications, procedures, techniques and other knowledge and information now or hereafter known to Inventor which are not in the public domain and which relate to the above-mentioned invention or improvement, its manufacture, uses or embodiments, or other matters (the "Related Know-How"). Inventor agrees to disclose or provide all Related Know-How to Assignee when discovered or upon request.

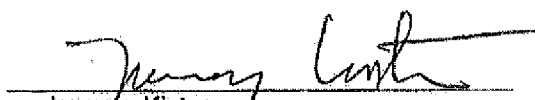
Inventor further covenants that Assignee will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to Inventor and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to Assignee or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof in any foreign country which may be necessary or desirable to carry out the purposes thereof.

Inventor's rights in the above-mentioned invention or improvement and Related Know-How and Letters Patent thereon have not been previously assigned, mortgaged or otherwise encumbered, and Inventor has full right, power and authority to assign all such rights to Assignee hereunder. Inventor previously assigned Serial No. 11/385,289, which is Patent No. 7,312,617, Space Transformers Employing Wire Bonds for Interconnections with Fine Pitch Contacts, to MicroProbe, Inc. on March 14, 2006 and is recorded at reel/frame: 017677/0712 on March 20, 2006.

As used herein, the terms "Inventor" and "Assignee" shall include such parties and their heirs, administrators, estates, successors and assigns of every kind.

Inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office, and all foreign countries' equivalent officials, to issue such Letters Patent as shall be granted on said application or applications based thereon to Assignee.

DATED this 18 day of June, 2010.


January Kister